



CyberOptics Demonstrates High-Precision Sensing Solutions to Improve Yield and Throughput at SEMICON West

Minneapolis, Minnesota — November 24, 2021 — [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high-precision 3D sensing technology solutions will feature the In-Line Particle Sensor™ (IPS™), and demonstrate WaferSense® and ReticleSense® sensors for semiconductor tool set-up and diagnostics at SEMICON West in San Francisco, California, from December 7-9th in booth 1639. The company will also demonstrate the NanoResolution Multi-Reflection Suppression™ (MRS™) sensor that is integrated into the WX3000™ Metrology and Inspection system for wafer-level and advanced packaging.

CyberOptics' IPS with CyberSpectrum™ software detects particles in gas and vacuum lines 24/7 in semiconductor process equipment and other controlled environments. It is particularly relevant for EUVL tools where the ability to monitor particles in-line can significantly improve tool yield and productivity. The IPS is an extension of the industry-leading WaferSense and ReticleSense Airborne Particle Sensor™ (APS™/APSRQ™) technology that is documented by fabs as the Best-Known Method (BKM). IPS quickly identifies, monitors and enables troubleshooting of particles down to 0.1µm. The effects of cleaning, adjustments and repairs can be seen in real-time. Equipment and process engineers can speed equipment qualification, shorten equipment maintenance cycles and lower equipment maintenance expenses.



“We continue to deploy our proprietary high-precision sensing technologies across various areas of fabs worldwide,” said Dr. Subodh Kulkarni, President and CEO, CyberOptics, “Whether it’s for semiconductor tool set-up and diagnostics, or inspection and metrology, we’re focused on enabling our customers to recognize significant improvements in yields, processes, productivity and throughput.”

The company also will feature the 3 µm NanoResolution MRS sensor that provides sub-micrometer accuracy on features as small as 25µm. The sensor is integrated into the WX3000 Metrology and Inspection system designed for wafer-level and advanced packaging applications. While retaining its ability to reject spurious multiple reflections, it adds the ability to capture and analyze specular reflections from shiny surfaces of solder balls, bumps and pillars, allowing highly accurate inspection and metrology of these critical packaging features. Fast, 100% 3D/2D inspection and metrology can be conducted with throughput greater than 25 wafers (300mm) per hour, 2-3X faster than alternative solutions.



For more information, visit www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (www.cyberoptics.com) is a leading global developer and manufacturer of high-precision 3D sensing technology solutions. CyberOptics' sensors are used for inspection and metrology in the SMT and semiconductor markets to significantly improve yields and productivity. By leveraging its leading-edge technologies, the Company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of key vertical markets. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: a possible worldwide recession or depression resulting from the economic consequences of the COVID-19 pandemic; the negative effect on our revenue and operating results of the COVID-19 crisis on our customers and suppliers and the global supply chain; market conditions in the global SMT and semiconductor capital equipment industries; trade relations between the United States and China and other countries; the timing of orders and shipments of our products, particularly our 3D MRS SQ3000 Multi-Function systems and MX systems for memory module inspection; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics and semiconductor markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; the market acceptance of our SQ3000 Multi-Function systems and products for semiconductor inspection and metrology; costly and time consuming litigation with third parties related to intellectual property infringement; the negative impact on our customers and suppliers due to past and future terrorist threats and attacks and any acts of war; the impact of the MX3000 orders on our consolidated gross margin percentage in any future period; risks related to cancellation or renegotiation of orders we have received; and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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